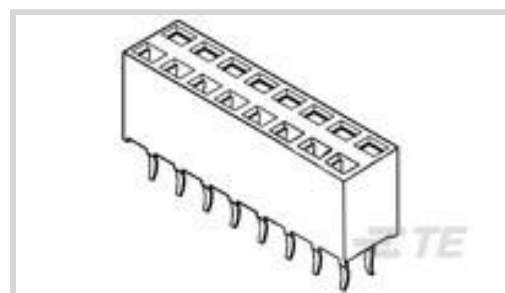




Connectors > PCB Connectors > Board-to-Board Connectors > Board-to-Board Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Receptacle**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Number of Positions: **4**

Centerline (Pitch): **2.54 mm [.1 in]**

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Receptacle
Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Number of Rows	2
Stackable	Yes
PCB Mount Orientation	Vertical
Number of Positions	4

Body Features

Connector Profile	Standard
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Contact Features

Contact Protection Type	Closed Entry Housing
Mating Square Post Dimension	.63 mm[.024 in]
PCB Contact Termination Area Plating Material Thickness	2.5 µm[98.425 µin]
Mating Pin Diameter	.63 mm[.024 in]
Contact Shape & Form	Square
PCB Contact Termination Area Plating Material	Tin



Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Gold
	30 µin
Contact Type	Socket
Contact Current Rating (Max)	3 A

Termination Features

Rectangular Termination Post & Tail Thickness	.2 mm[.008 in]
Rectangular Termination Post & Tail Width	.69 mm[.027 in]
Termination Post & Tail Length	3.1 mm[.122 in]
Termination Method to Printed Circuit Board	Through Hole - Solder

Mechanical Attachment

PCB Mount Retention Type	Retention Solder Tails
PCB Mount Retention	With

Housing Features

Mating Entry Location	Top
Centerline (Pitch)	2.54 mm[.1 in]
Housing Color	Black
Housing Material	Polyester - GF

Dimensions

Connector Height	8.5 mm[.335 in]
Row-to-Row Spacing	2.54 mm[.1 in]
PCB Thickness (Recommended)	1.6 mm

Usage Conditions

Operating Temperature Range	-65 – 125 °C
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Operation/Application

Solder Process Feature	Board Standoff
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Quantity	352
Packaging Method	Carton

Product Compliance

For compliance documentation, visit the product page on [TE.com](https://www.te.com)>

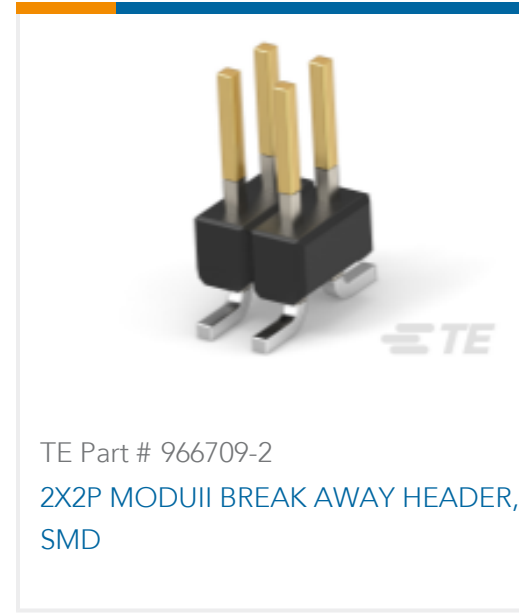
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUL 2021 (219) Candidate List Declared Against: JAN 2021 (211) SVHC > Threshold: Not Yet Reviewed
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

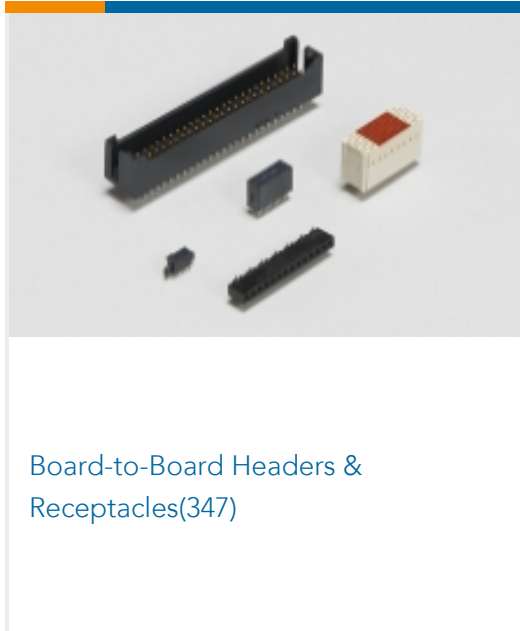
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts

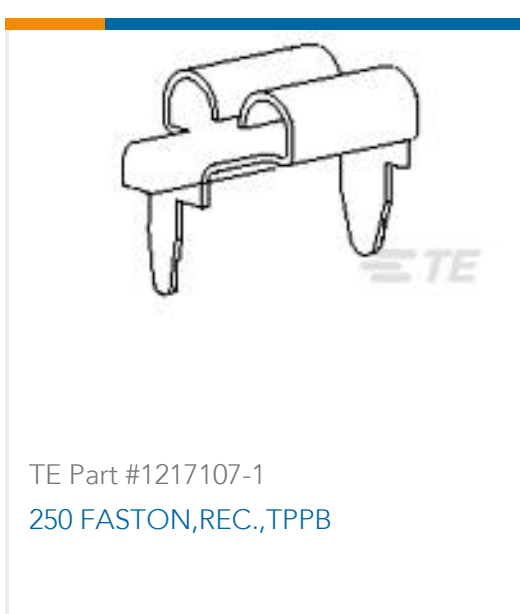
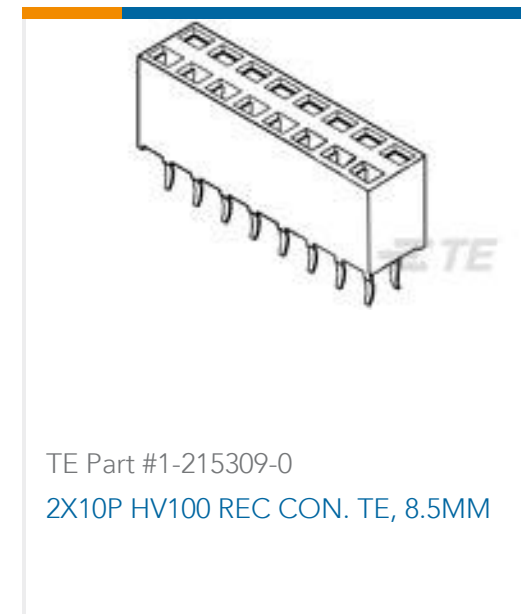
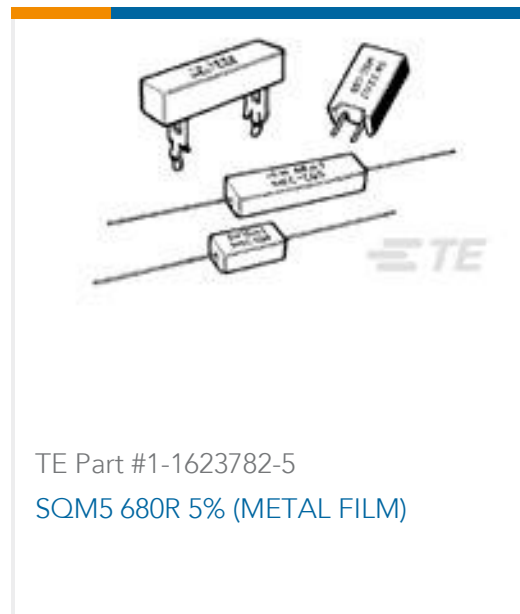
 <p>TE Part # 1241050-2 2x2P MOD II BREAK AWAY HDR,SMD, BLISTER</p>	 <p>TE Part # 826632-2 2P AMPMODU II II PIN HDR</p>	 <p>TE Part # 826662-2 2P AMPMODU II STIFT LEI</p>	 <p>TE Part # 826634-2 2P MOD2 STIFT LEI</p>
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Also in the Series | **AMPMODU HV-100/HV-190**



Customers Also Bought





Documents

Product Drawings

[2X2P HV100 REC CON. TE, 8.5MM](#)

English

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_215309-2_E.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_215309-2_E.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_215309-2_E.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Environmental Compliance

[TE Material Declaration](#)

English